

DIAPOL 5174 C, high flexible

Temperature resistance -50°C + 130°C



PRODUCT DESCRIPTION

- ✓ Resin without solvent
- ✓ 100% polymerizing
- ✓ Low level of water absorption
- ✓ Hardening at room temperature
- ✓ No chemical aggression
- ✓ Low exothermic reaction
- ✓ Keeps flexibility below 0 degrees

APPLICATION

Molding resin has multiple electrical and electronic applications which works below 0 degrees is required (e.g. Cable connectors, printed circuits, the car industry, etc.).

HOW TO USE

DIAPOL 5174 C resin is supplied in two separate and pre-dosed components: a black resin and a 510 catalyst. The mixture weight ratio (resin / catalyst) is 100/10. Hermetic and sealed containers must be stored at room temperature (15-25°C), thus ensuring a shelf life of 1 year. Due to the fact that the mineral content over time settles on the bottom of the container, the resin must be well mixed before use. DIAPOL 5174 C resin can be mixed with the catalyst at room temperature in a dose of 100/10. It is recommended to use automatic mixing / dosing devices to operate this product. If you want to peel off the polymerized resin, we recommend using our EUROSILICON spray. In the case of closed parts, which must have maximum electrical characteristics, it is recommended that the forming takes place in a vacuum.

CHARACTERISTICS

	DIAPOL 5174	CATALIZATOR 500	MIX 100/10
Viscosity at 25°C (mPa·s)	6000 ± 2000	150 ± 50	5000 ± 1000
Density at 20°C (g/cm ³)	1,7 ± 0,04	1,18 ± 0,01	1,65 ± 0,02
Pot Life at 25°C (min)	40-50		
Complete polymerization	8 hours at 60°C		
Shore A hardness	35 ± 5		
Dielectric strength 50Hz, 20°C (kV/mm)	12		
Thermal conductivity (W/mK)	0.5-0.6		

PACKAGES

The product is available in 1kg, 5kg and 25kg packages. Available on request in packages of 140kg, 300kg and 1000kg.